
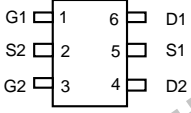


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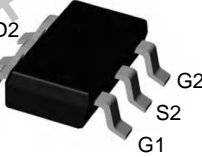
N+P-Channel Enhancement Mode Mosfet

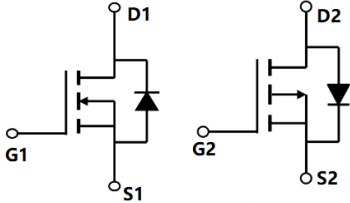
<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>N Channel</p> <p>$V_{DS} = 40V, I_D = 5.8A$ $R_{DS(ON)} = 30m\Omega (Typ.) @ V_{GS} = 10V$</p> <p>P Channel</p> <p>$V_{DS} = -40V, I_D = -4.9A$ $R_{DS(ON)} = 77m\Omega (Typ.) @ V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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MI6: SOT-23-6L



Marking: 4614C





Absolute Maximum Ratings: ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Units
V_{DS}	Drain-Source Voltage	40	-40	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Continuous Drain Current- $T_C = 25^\circ C$	5.8	-4.9	A
	Continuous Drain Current- $T_C = 100^\circ C$	3	-2.7	
I_{DM}	300 μs Pulsed Drain Current	25.2	-16.8	A
P_D	Power Dissipation	1.83	1.83	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175		$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	68	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	---	$^\circ C/W$

TM4614CM16

N+P-Channel Enhancement Mode Mosfet

N-Channel Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

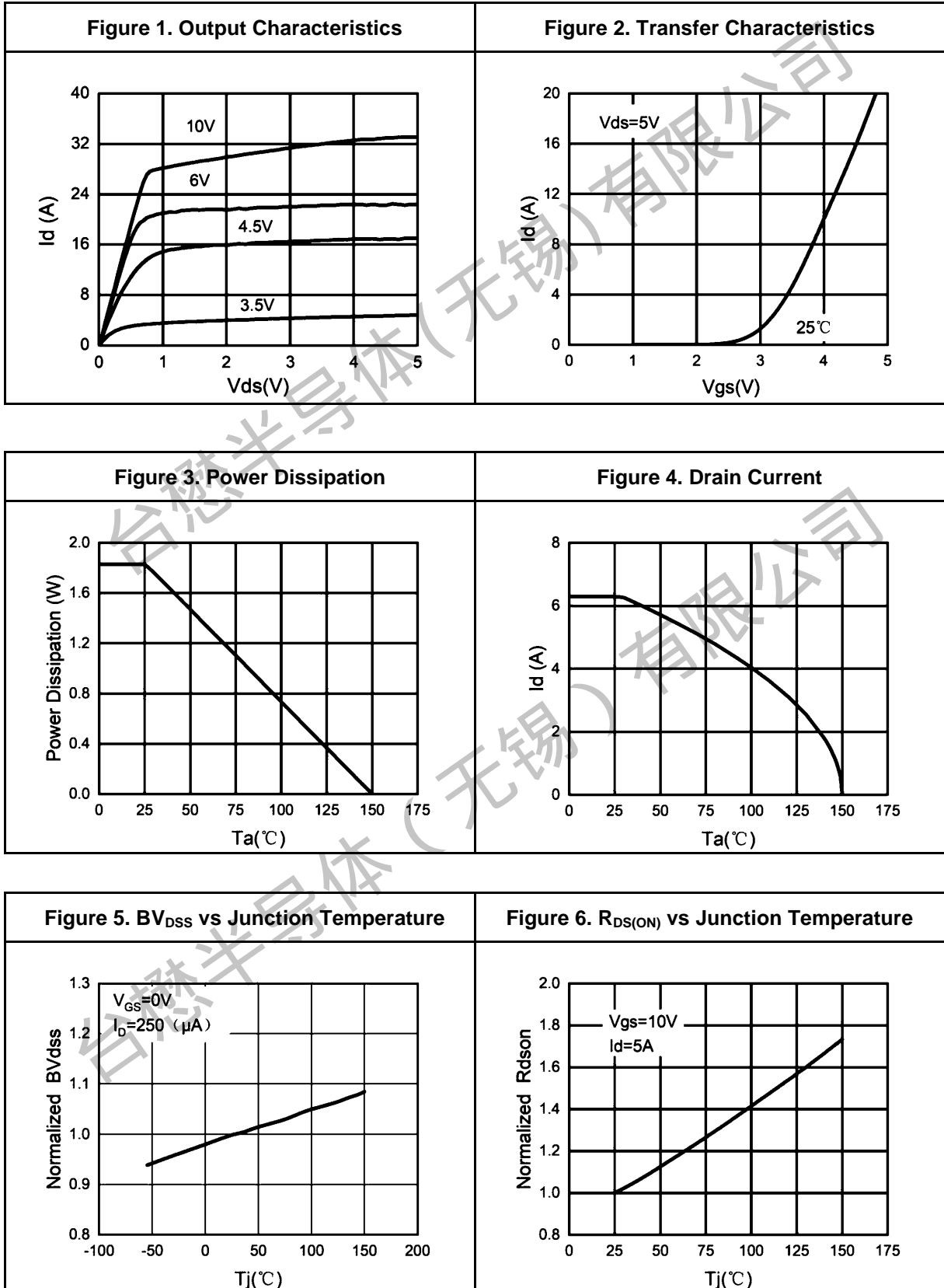
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ C$			1	μA
		$V_{DS}=40V, V_{GS}=0V, T_J=125^\circ C$			100	μA
I _{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.6	2.0	V
g _{FS}	Forward Transconductance	$V_{DS}=5V, I_D=5A$		6		S
R _{DS(ON)}	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=5A, T_J=25^\circ C$		30	35	m Ω
R _{DS(ON)}	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=4A, T_J=25^\circ C$		40	50	m Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, f=1.0MHz$		777		pF
C _{oss}	Output Capacitance			55		pF
C _{rss}	Reverse Transfer Capacitance			34		pF
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=20V, R_L=3.3\Omega, R_{GEN}=3\Omega$		5		nS
t _r	Turn-on Rise Time			2.5		nS
t _{d(off)}	Turn-Off Delay Time			18		nS
t _f	Turn-Off Fall Time			2.6		nS
Q _g	Total Gate Charge	$V_{GS}=10V, V_{DS}=20V, I_D=5A$		10		nC
Q _{gs}	Gate-Source Charge			2.7		nC
Q _{gd}	Gate-Drain Charge			2.6		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				5.8	A
V _{SD}	Forward on Voltage	$V_{GS}=0V, I_S=5A$			1.2	V



TM4614CM16

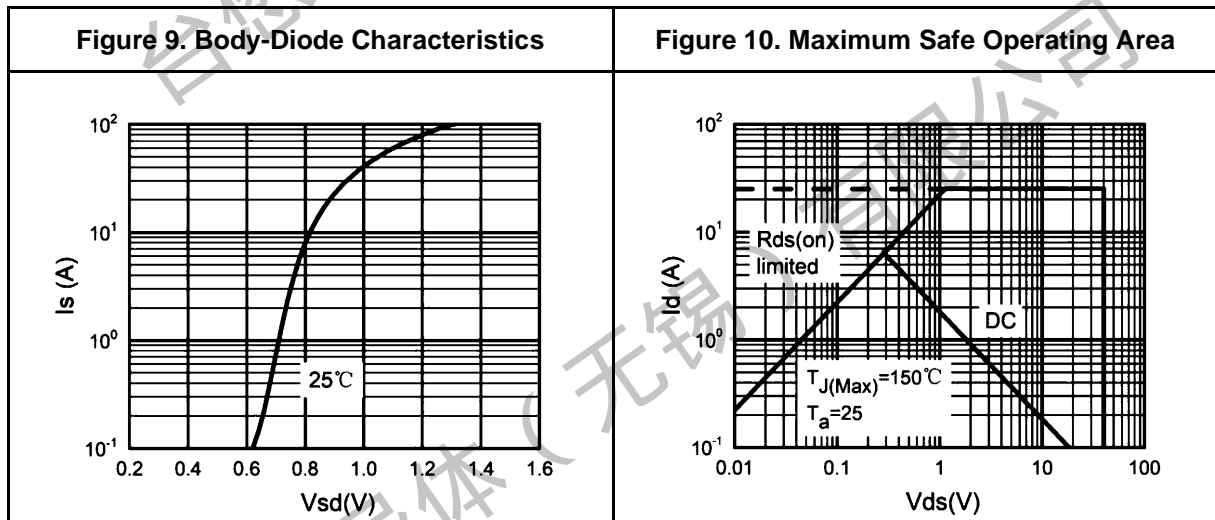
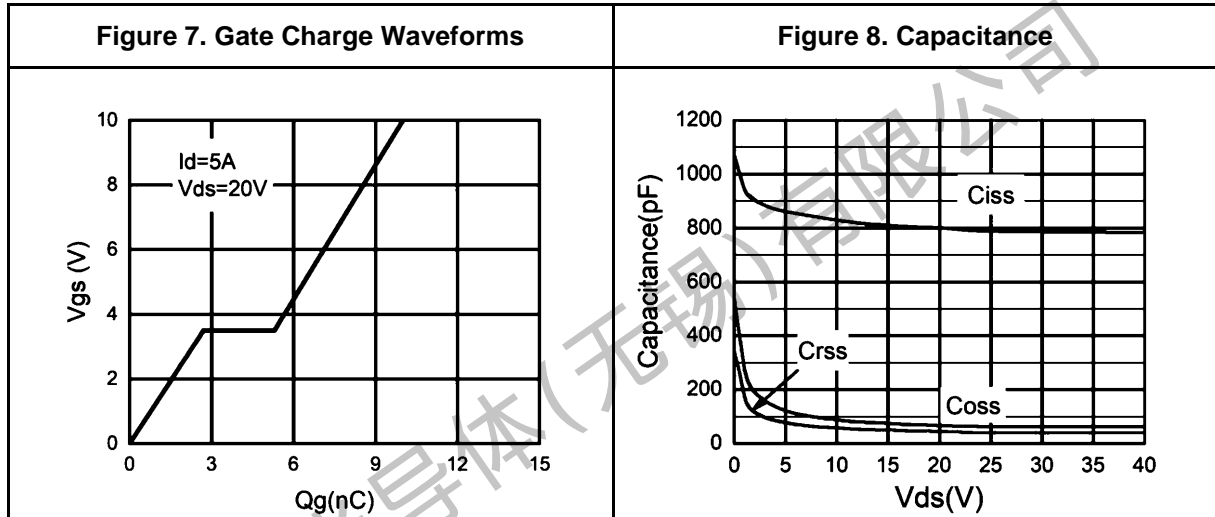
N+P-Channel Enhancement Mode Mosfet

N-Channel Typical Electrical And Thermal Characteristics (Curves)



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N+P-Channel Enhancement Mode Mosfet



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N+P-Channel Enhancement Mode Mosfet

P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

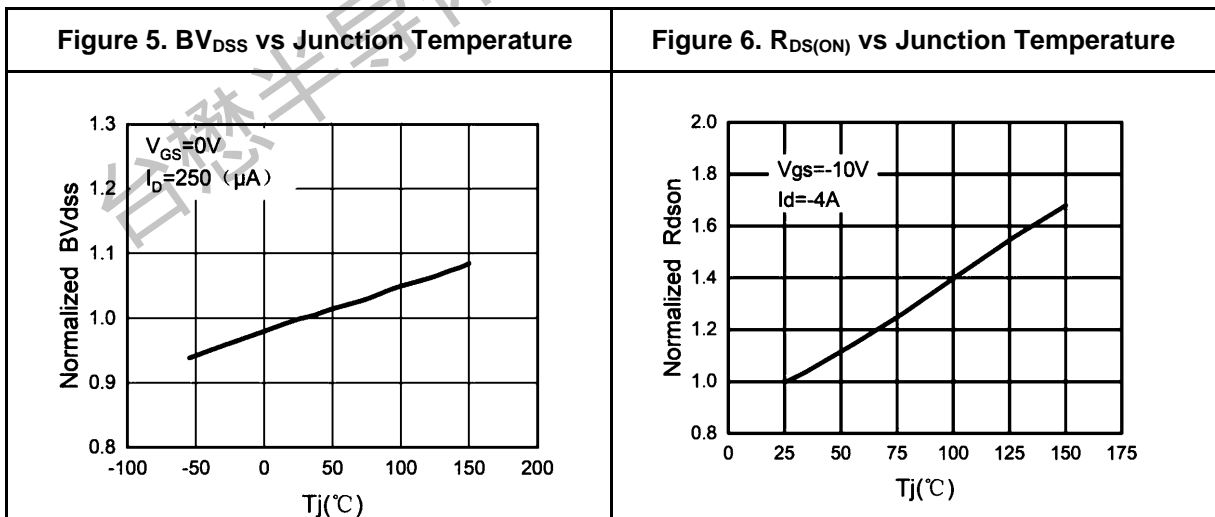
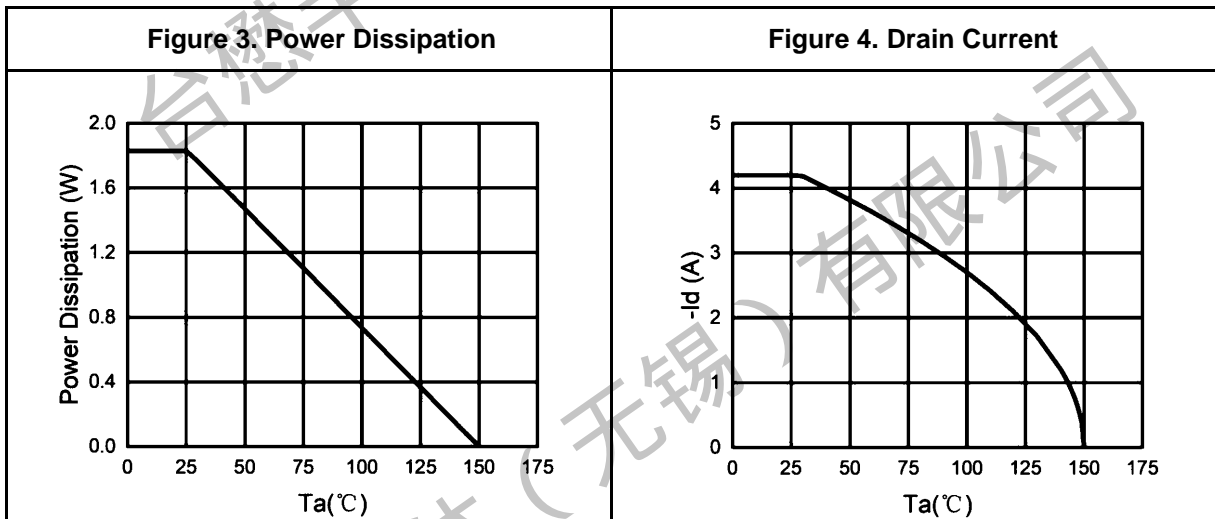
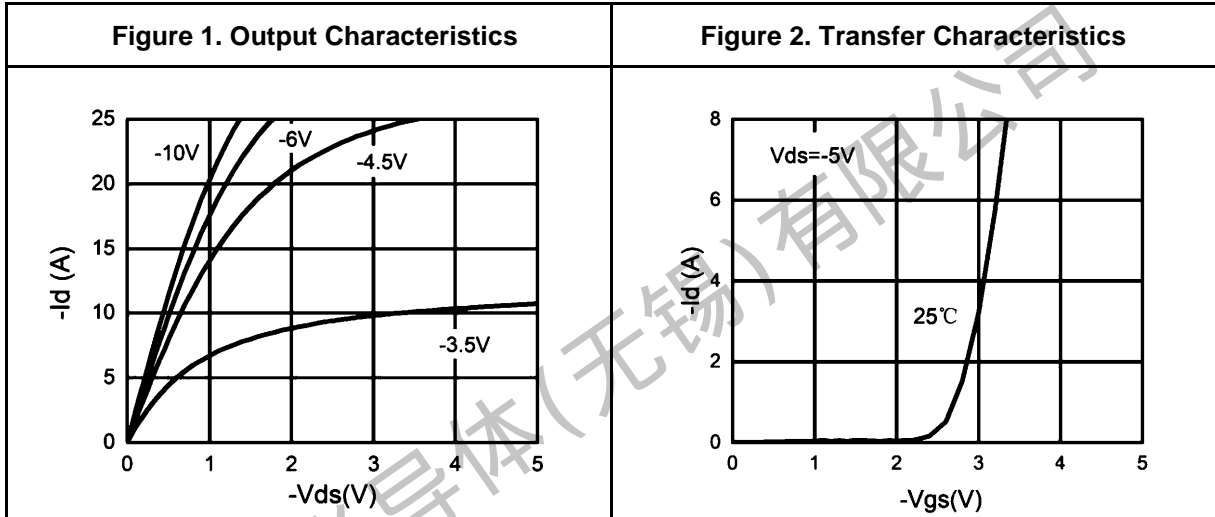
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-40			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-40V, V _{GS} =0V T _J =25°C			-1	μA
		V _{DS} =-40V, V _{GS} =0V T _J =125°C			-100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.75	-2.5	V
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-4A		8		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-4A T _J =25°C		77	82	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-3A T _J =25°C		95	100	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-20V, V _{GS} =0V, f=1.0MHz		900		pF
C _{oss}	Output Capacitance			61		pF
C _{rss}	Reverse Transfer Capacitance			45		pF
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-20V, R _L =5Ω, R _{GEN} =3Ω		7.5		nS
t _r	Turn-on Rise Time			3.5		nS
t _{d(off)}	Turn-Off Delay Time			18		nS
t _f	Turn-Off Fall Time			4.5		nS
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-20V, I _D =-4A		11		nC
Q _{gs}	Gate-Source Charge			3.3		nC
Q _{gd}	Gate-Drain Charge			2.7		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				-4.9	A
V _{SD}	Forward on Voltage	V _{GS} =0V, I _S =-4A			-1.2	V



TM4614CM16

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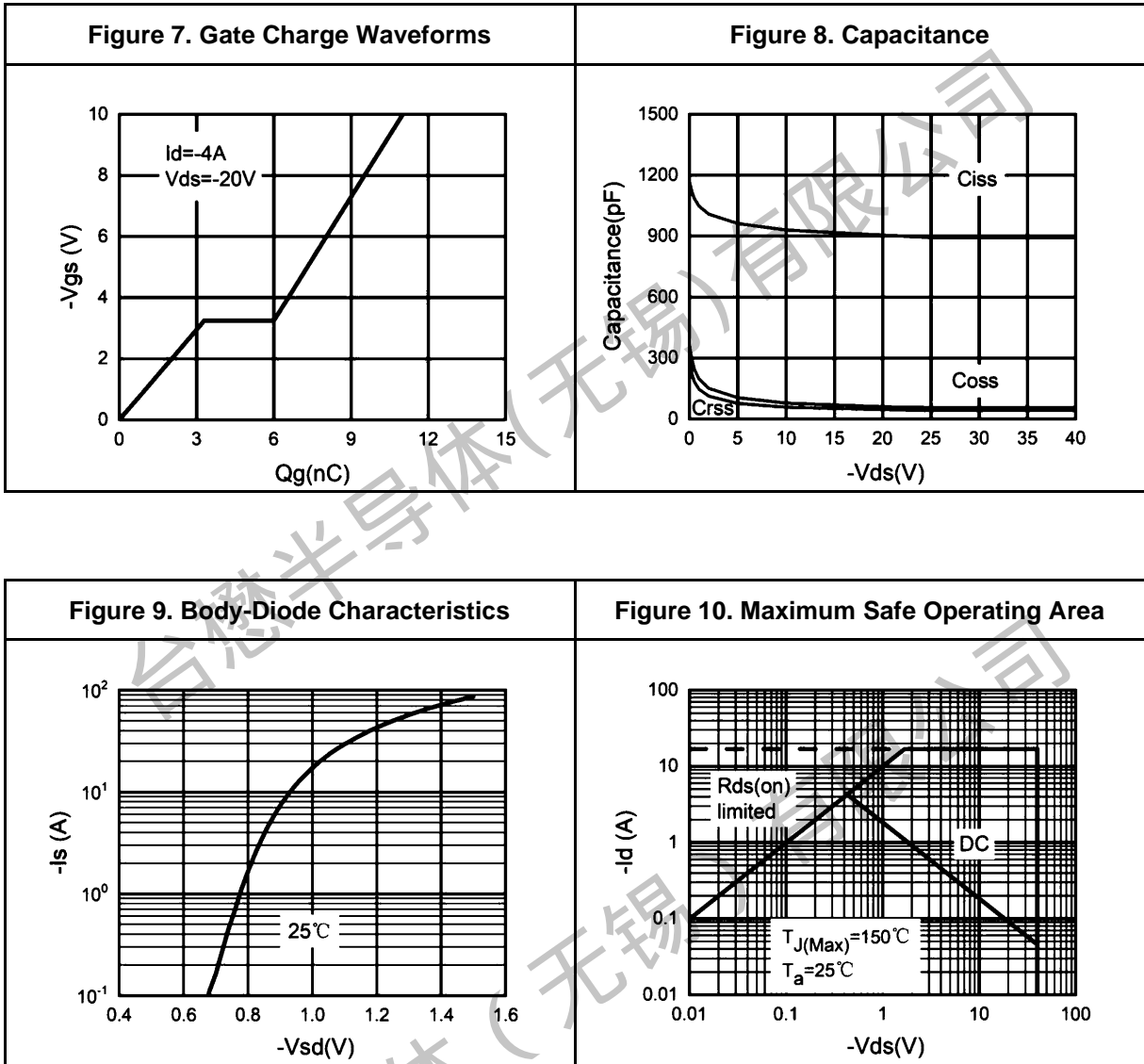
P-Channel Typical Electrical And Thermal Characteristics (Curves)





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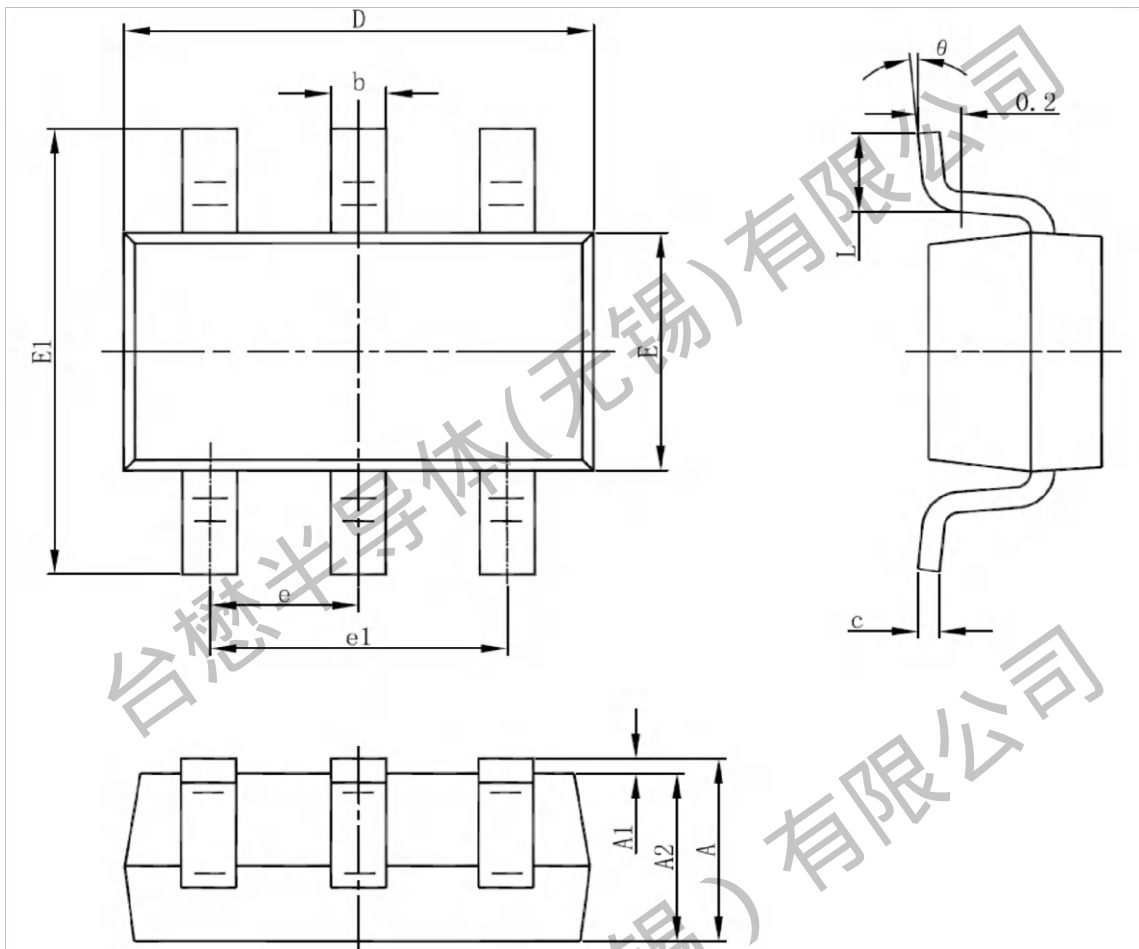
N+P-Channel Enhancement Mode Mosfet



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N+P-Channel Enhancement Mode Mosfet

Package Mechanical Data :SOT-23-6L



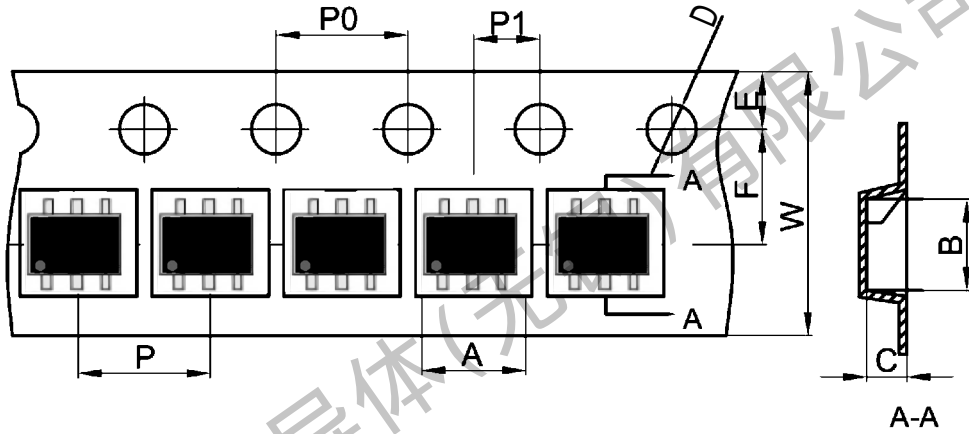
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°



TM4614CM16

N+P-Channel Enhancement Mode Mosfet

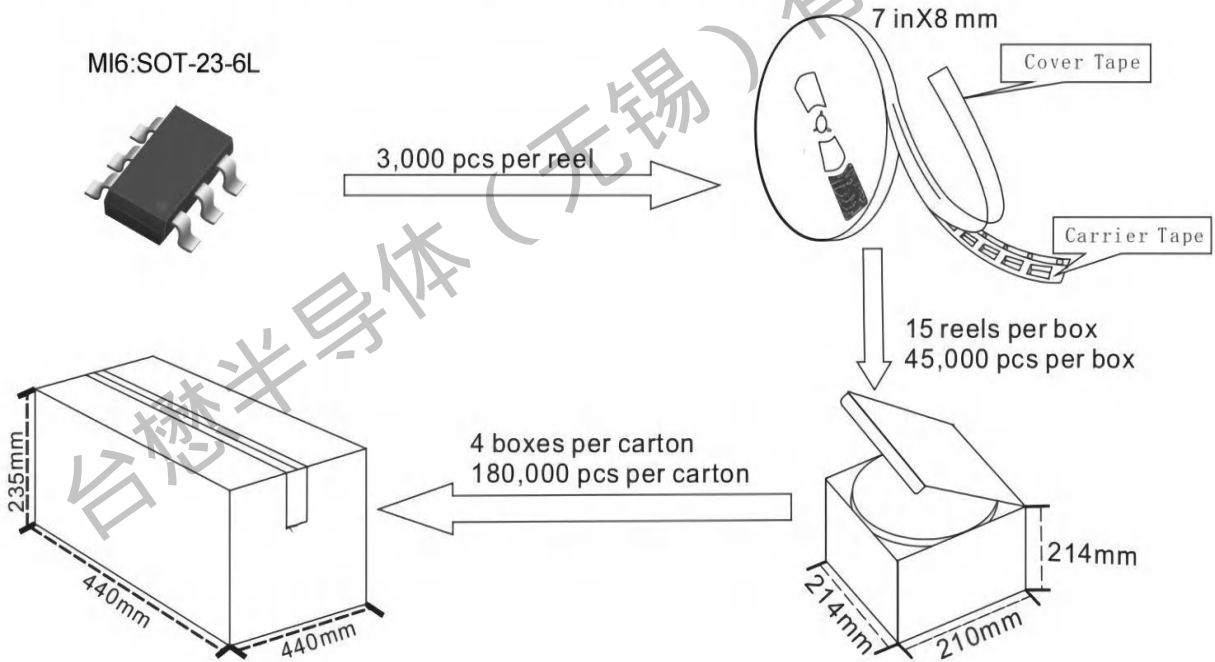
SOT-23-6L Embossed Carrier Tape



Dimensions are in millimeter										
Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23-6L	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23-6L Packing

The method of packaging and dimension are shown as below figure. (Dimension in mm)



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Revision history:

Date	Rev	Description	Page
2023.06.22	23.06	Original	